

# Industrial AI Technology and Software Platform for Manufacturing

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# Today

- 1 Why Manufacturing AI?

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- 2 Computer vision ML for manufacturing

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- 3 Time-series ML for manufacturing

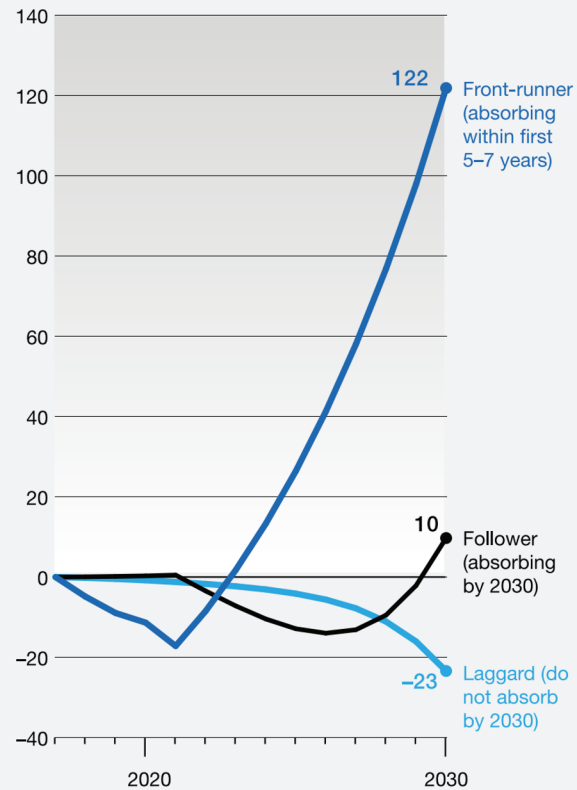
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- 4 Difficulties with time-series ML in manufacturing

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- 5 Gauss Labs success story: Virtual Metrology

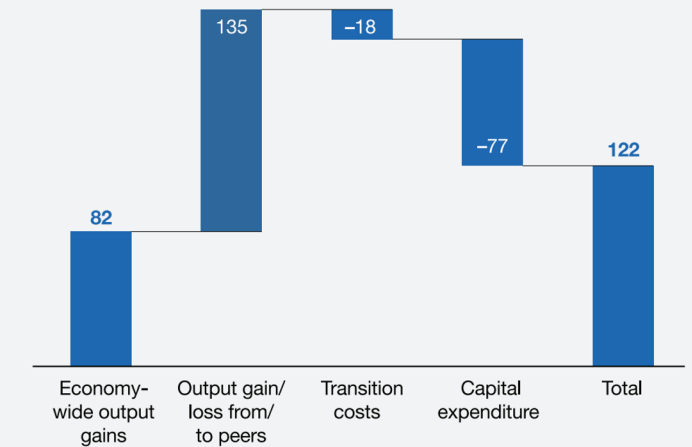
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Fast AI adoption  
 WILL create **way**  
 larger economic  
 gains

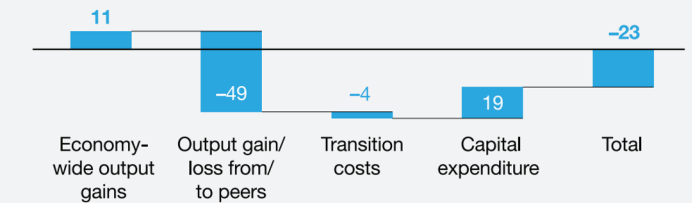
Relative changes in cash flow by AI-adoption cohort, cumulative % change per cohort



Front-runner breakdown, % change per cohort



Laggard breakdown, % change per cohort



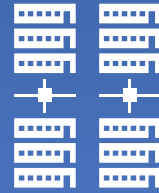
Note: Numbers are simulated figures to provide directional perspectives rather than forecasts.

\* Source: McKinsey Global Institute Analysis (2019)

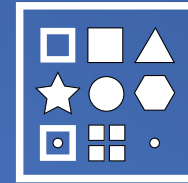
## Data Characteristics

Virtuous (or Vicious) Cycle

Data-centric AI



Volume



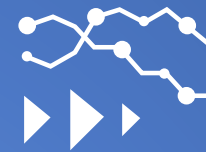
Variety



Velocity



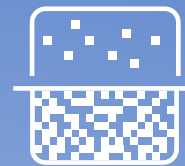
FatData



Shift/drift



Imbalance



Quality



Nonlinearity

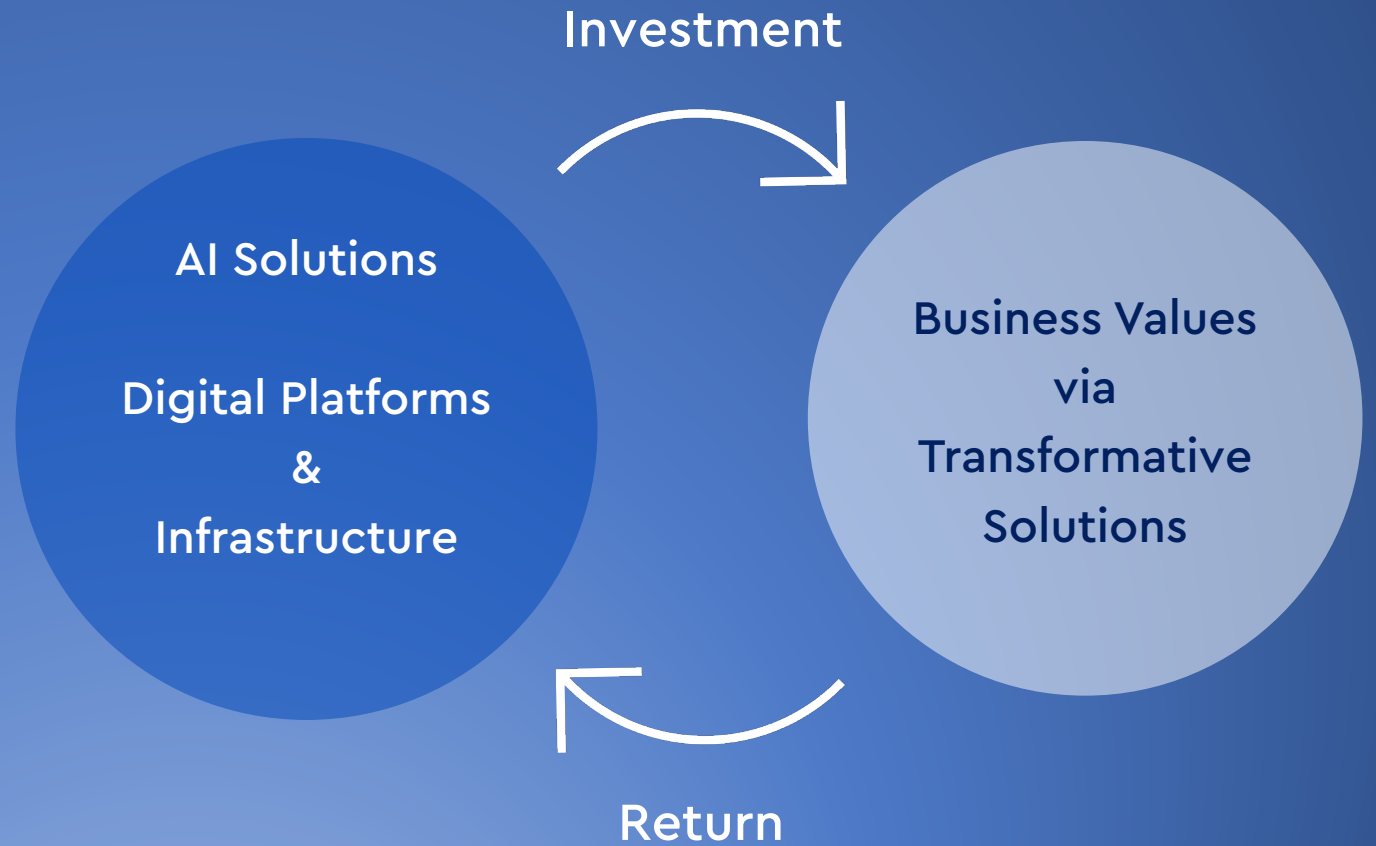


Complexity

**Data Characteristics**

**Virtuous (or Vicious) Cycle**

**Data-centric AI**



"We need 1,000 models for 1,000 problems" – Andrew Ng

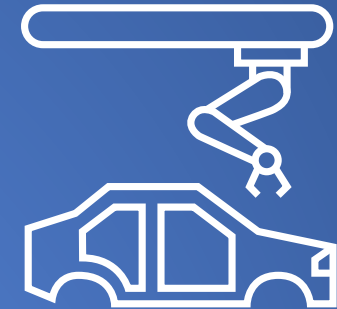
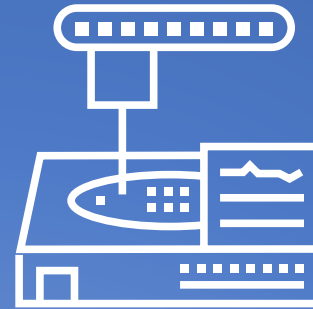
## Data-centric AI

Discipline of systematically engineering the data used to build an AI system

## Data Characteristics

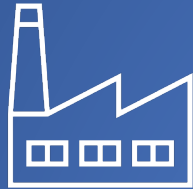
Virtuous (or Vicious) Cycle

**Data-centric AI**



Every company or sector has its own problems

# Our initial focus for 10x changes

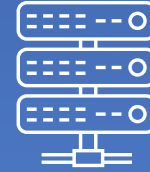


## Semiconductor Fab

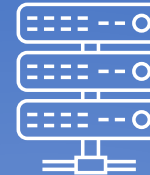
### A modern mega fab has ...

- ~1,000 process equipment
- ~100 metrology equipment
- ~1,000 wafers per day, per equipment
- ~1,000 processes per wafer
- 3-6-month cycle time

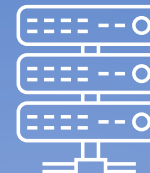
## Servers and Systems



Equipment Sensor Data  
(~1M parameters, ~1Tb/day)



Metrology Image Data  
(~1M images, ~10 Tb/day)



Manufacturing Execution Data  
(~10M events, ~10 Gb/day)

## Why Semiconductor?

Data availability from advanced digitalization

Diverse and sophisticated processes, ideal for expanding to new customers & sectors

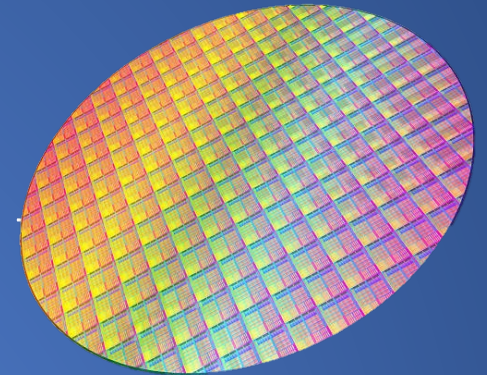
Huge impact even within the sector itself

# Computer vision and time-series ML in Manufacturing

## lots of image data to measure and inspect

Scanning electron microscope (SEM) images, transmission electron microscope (TEM) images, etc.

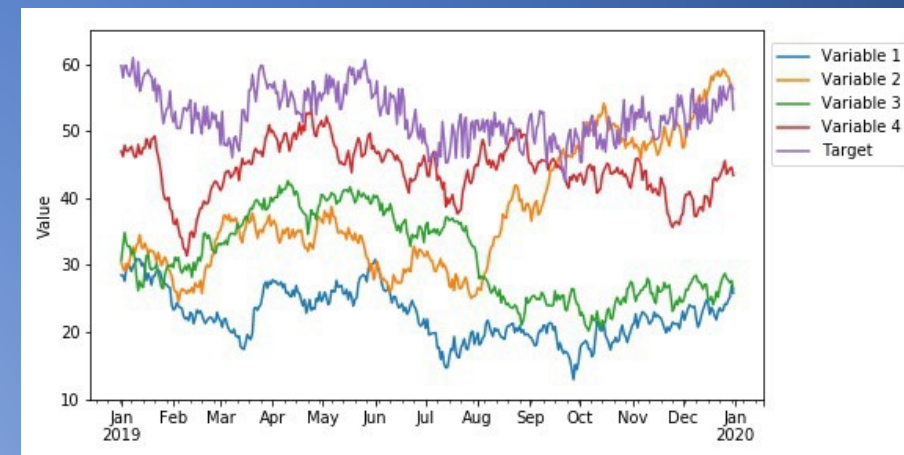
→ Image pattern classification, image anomaly detection, defect inspection, etc.



## (almost) All the data coming from manufacturing are time-series data

Equipment sensor data, process times, material measurement, etc.

→ time-series (TS) regression / prediction/estimation, TS anomaly detection, etc.





# Computer Vision ML for manufacturing



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## **Metrology**

*Measurement of critical features*

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## **Inspection**

*Anomaly detection,  
localization and classification*

Image courtesy of ASML

# Scanning Electron Microscope

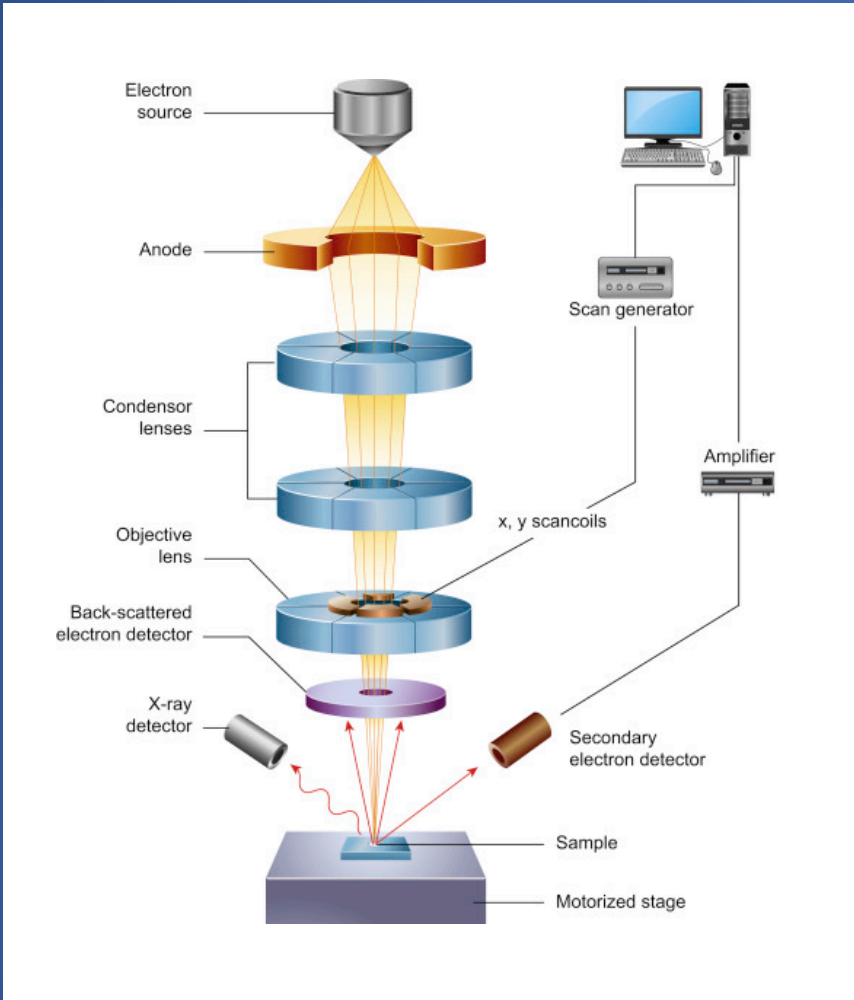
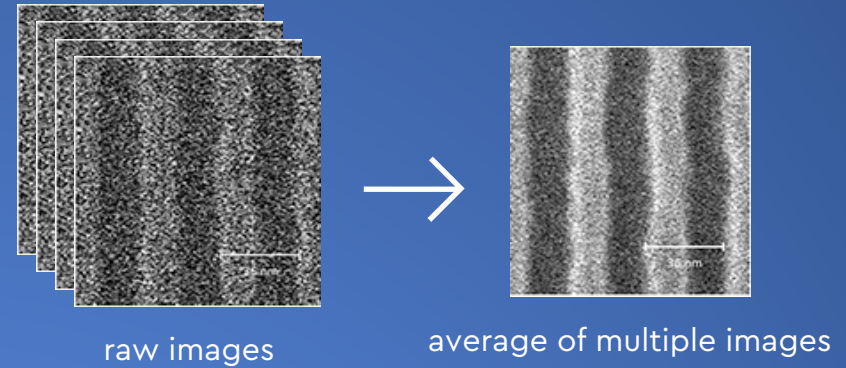


Image courtesy of <https://www.sciencedirect.com/science/article/pii/S9780081000403000002X>



Shot Noise Image courtesy of [https://en.wikipedia.org/wiki/Shot\\_noise](https://en.wikipedia.org/wiki/Shot_noise)

# Image restoration

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## Inverse problem of image corruption

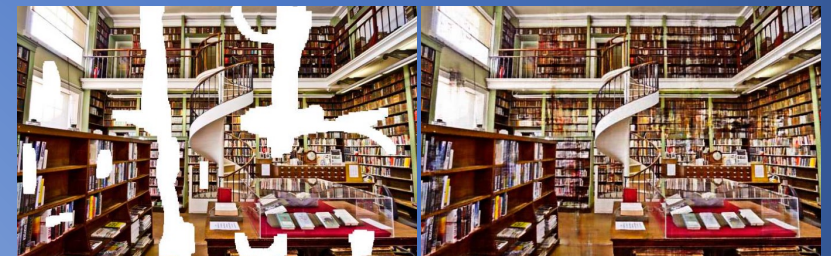
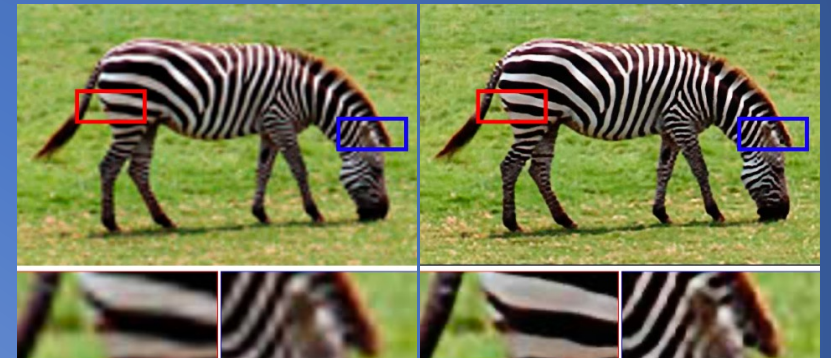
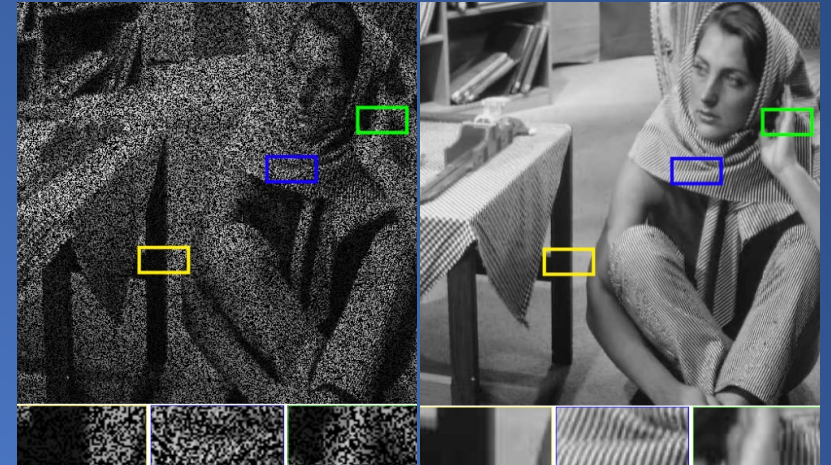
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$$x = f(y) + n$$

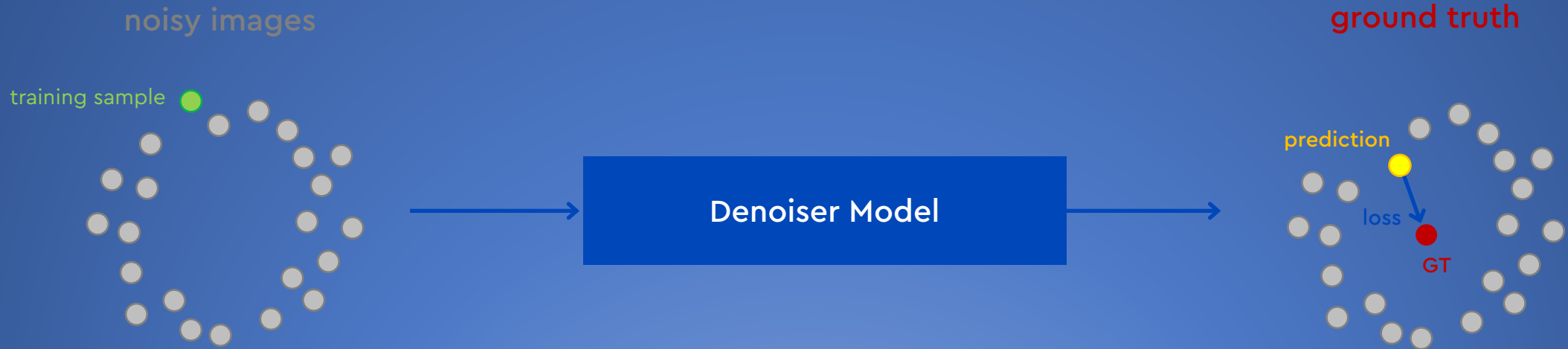
- $y$ : clean image
- $x$ : corrupted image
- $n$ : noise

## $f(\cdot)$ and corresponding solutions

- Noising: Identity function  $\rightarrow$  Denoising
- Downsampling  $\rightarrow$  Super-resolution
- Missing pixels  $\rightarrow$  Inpainting

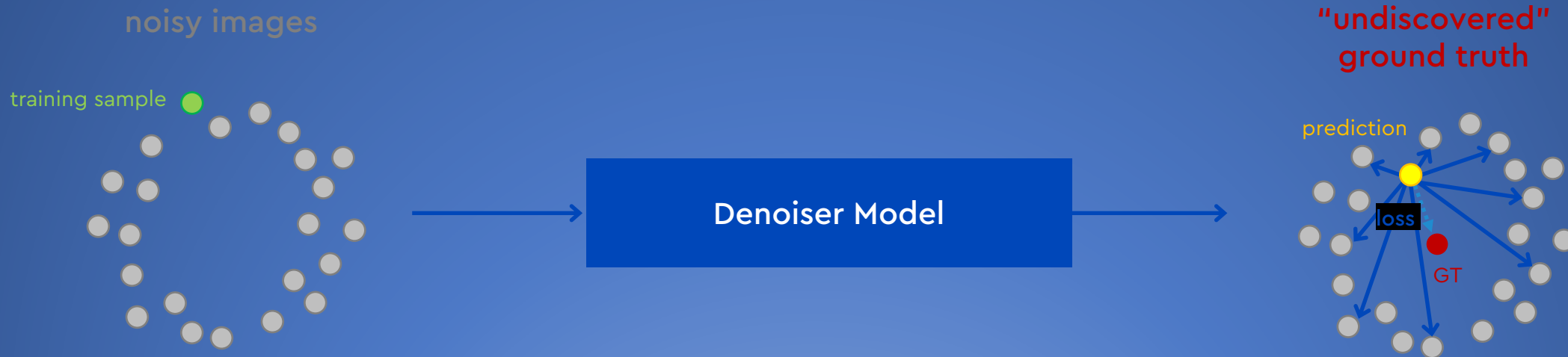


# Supervised image denoising



*However, it is not possible to acquire ground-truth images from SEM device, in practice.*

# Blind denoising without ground truth



*If the mean of the noise is zero, the average of the gradients that model takes is same with the gradient to the ground truth*

# Metrology based on segmentation and pattern recognition

Investment

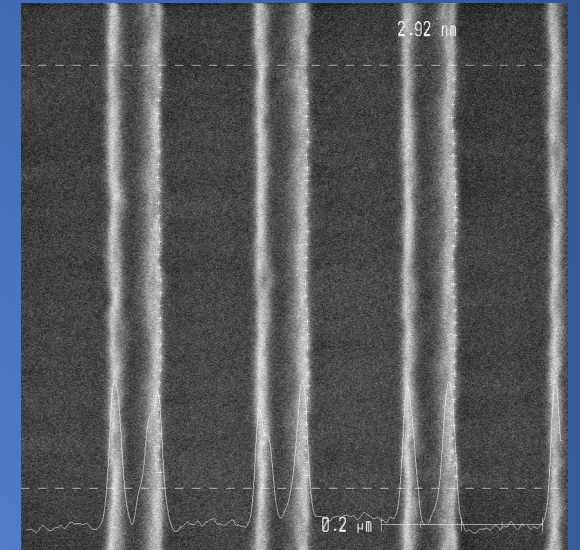
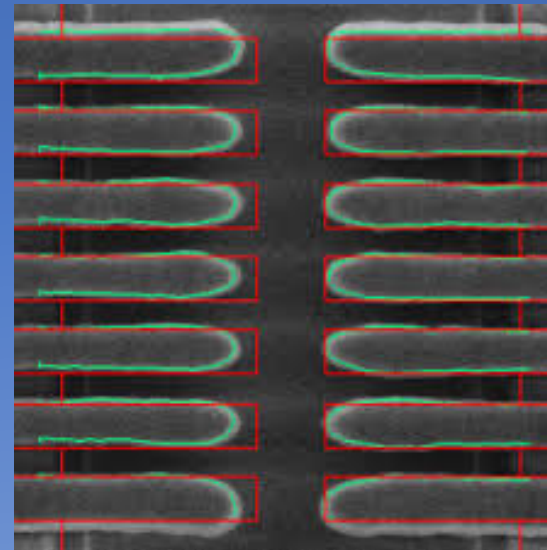
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Automatic measurement of  
critical dimensions

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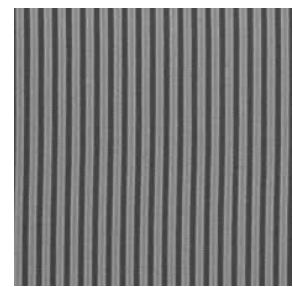
## Approaches

- Unsupervised texture segmentation
- Repetitive pattern recognition

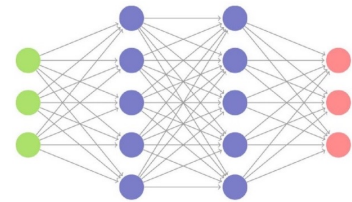


<0.1 nm measurement precision guaranteed

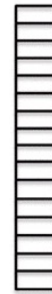
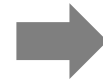
# Anomaly detection in unsupervised learning



input image



pretrained NN



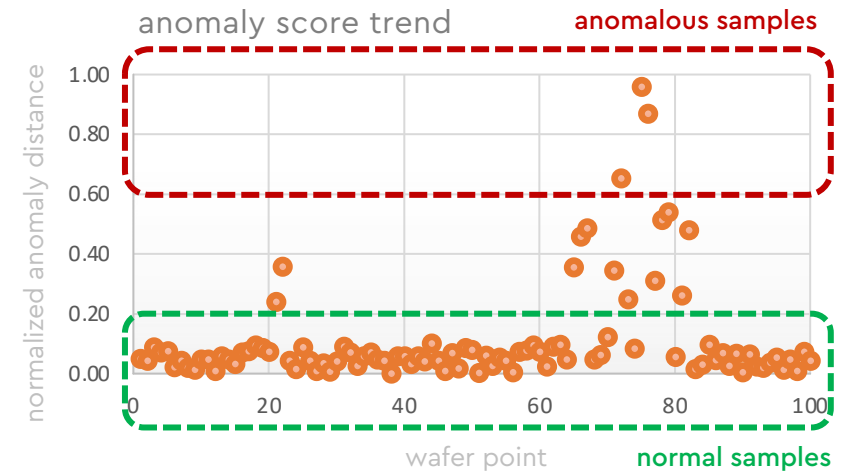
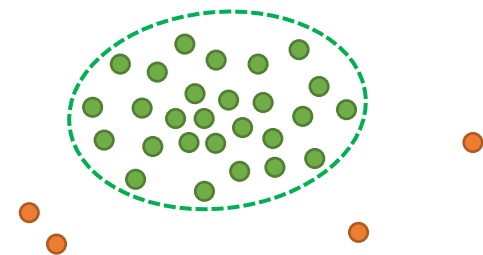
feature vector

distance to the normal vector cluster in kNN

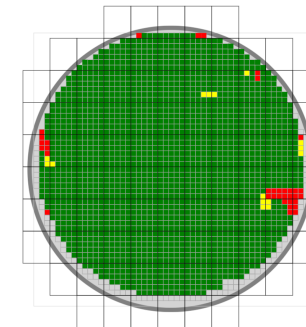


precomputed in unsupervised learning

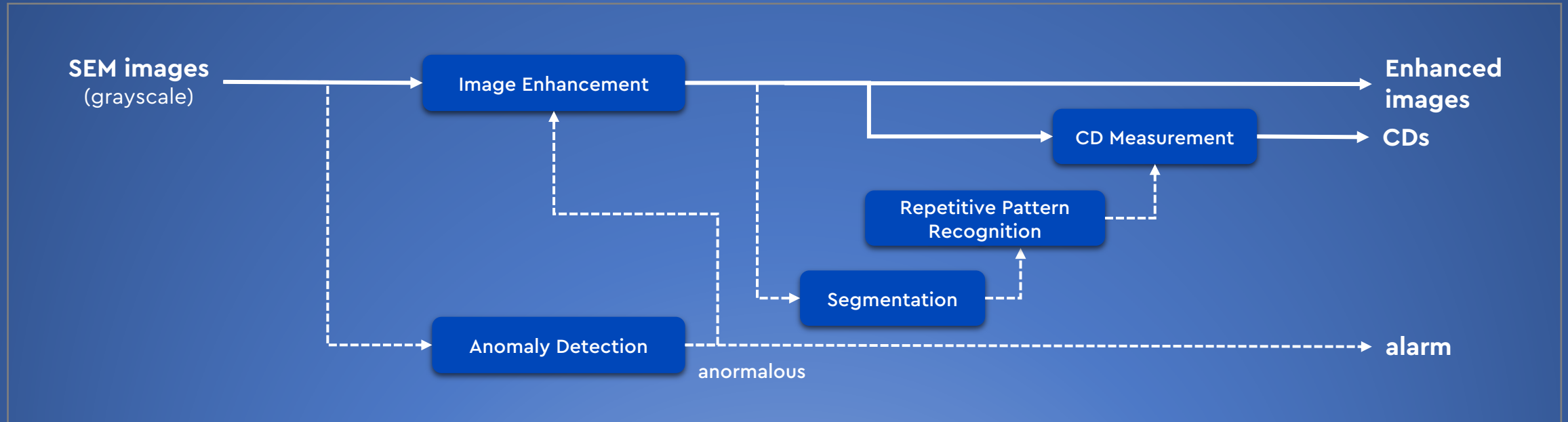
vectors of normal images  
vectors of anomalous images



anomaly score wafer map

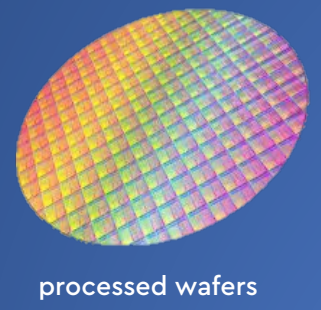


# AI-accelerated metrology system

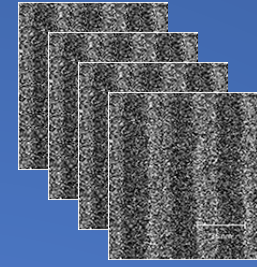




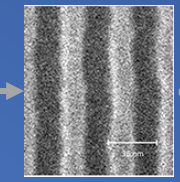
# Automatic measurement for semiconductor manufacturing



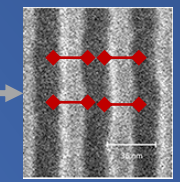
Scanning Electron Microscope (SEM)



raw images



average of multiple images



measure

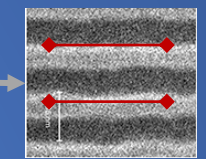
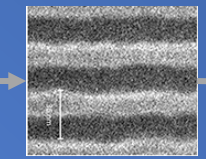
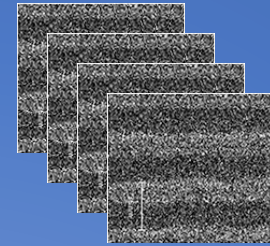
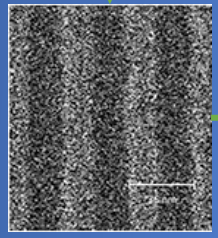
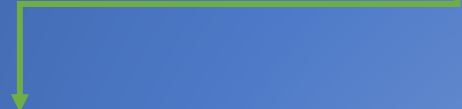
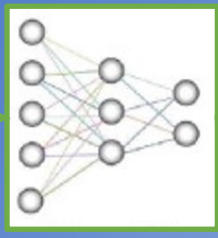


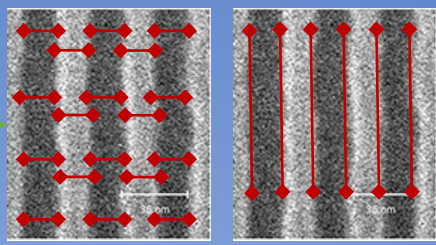
image capture



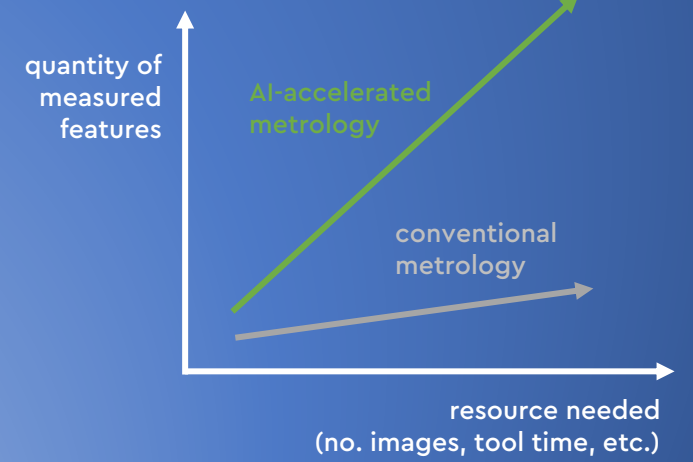
raw image



AI metrology algorithms



automatic measurement in enhanced image

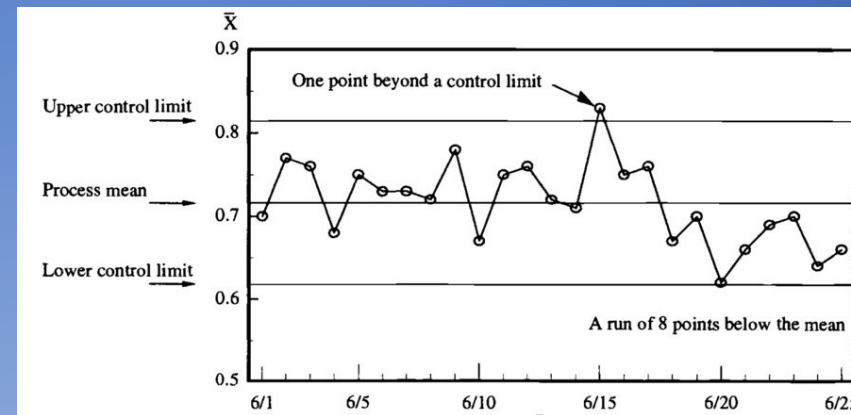
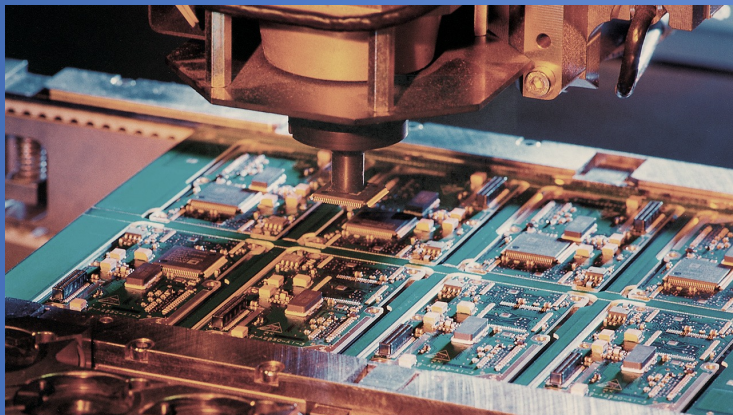


# Time-series ML for manufacturing

# Why time-series ML?

*manufacturing application is about one of the followings:*

- prediction of time-series values - virtual metrology, yield prediction
- classification of time-series values - equipment anomaly alarm generation
- anomaly detection on time-series data - root cause analysis, yield analysis



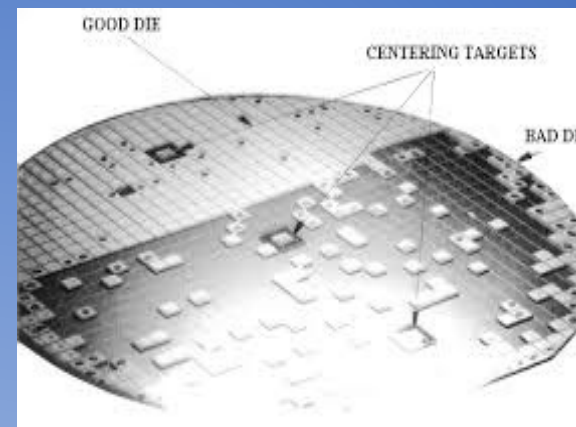
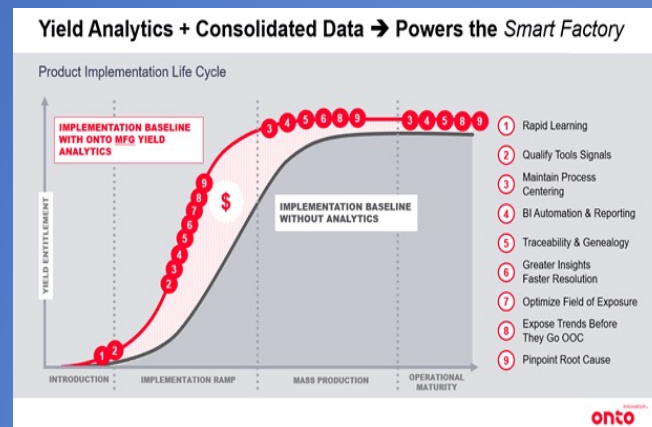
# Time-series regression/prediction/estimation

- virtual metrology

- *measure unmeasured* processed materials using equipment sensor signals
- *save investment on measurement equipment, downstream applications such as process control, statistical process control, yield improvement*

- yield prediction

- *predict yield (# working dies / # total dies)*
- *better product quality and larger profit, business impact*



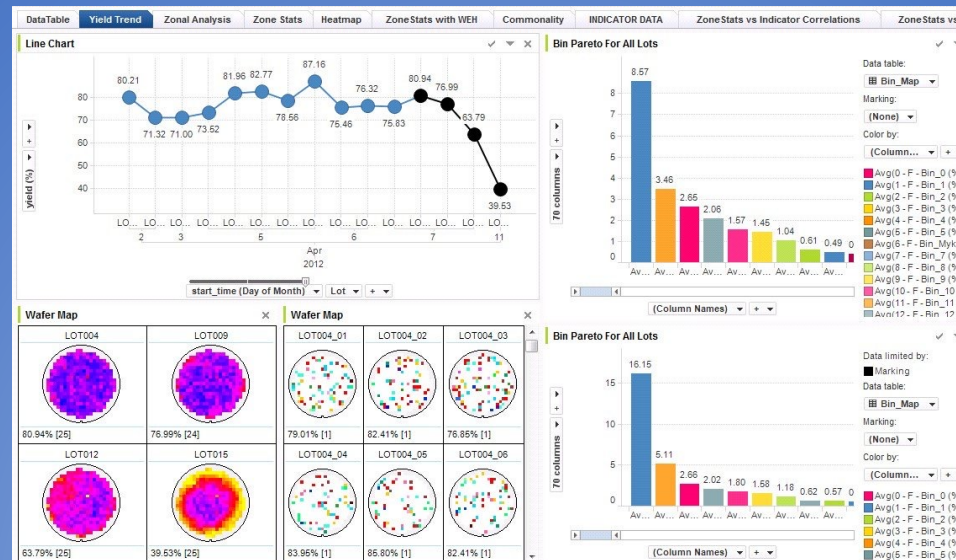
# Root cause analysis using time-series anomaly detection

- equipment alarm root cause analysis

- when alarm goes off, find responsible equipment and root causes
- reduce equipment downtime, make *process engineers' lives easier*

- yield analysis

- find responsible equipment and root causes for yield drop
- a few % yield improvement brings profit increase of tens of millions of dollars!



# Difficulties with Time-series ML in manufacturing

# Data challenges

- covariate shift & concept drift

$p(x(t_k), x(t_{k-1}), \dots)$  changes over time

$p(y(t_k) | x(t_k), x(t_{k-1}), \dots, y(t_{k-1}), y(t_{k-2}), \dots)$  changes over time

- fat data, *i.e.*, # features way larger than # data
- poor data quality; missing values, anomalies, wrong formats
- huge volume of data to process
- multi-modality - different types of data

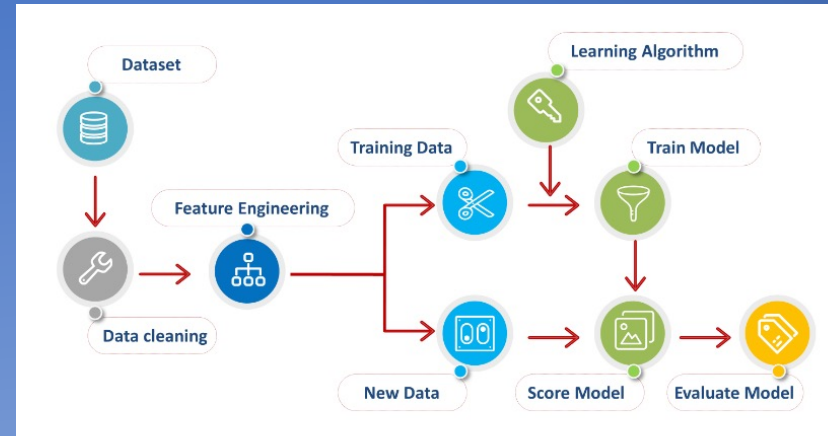
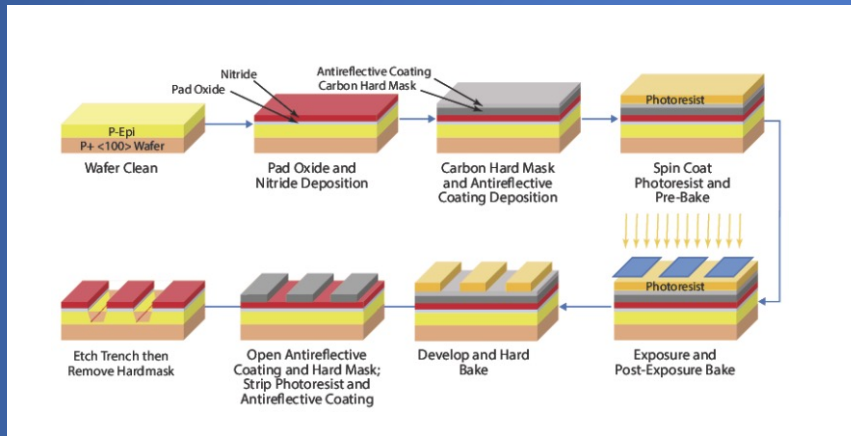
# Domain knowledge and fully home-grown algorithms

*in most cases,  
domain knowledge is critical!*

close collaboration with customers required

*off-the-shelf algorithms  
not working!*

developing fully customized algorithms needed





# Virtual Metrology (VM)

# What is VM?

*in many cases,  
we cannot measure all  
processed materials*

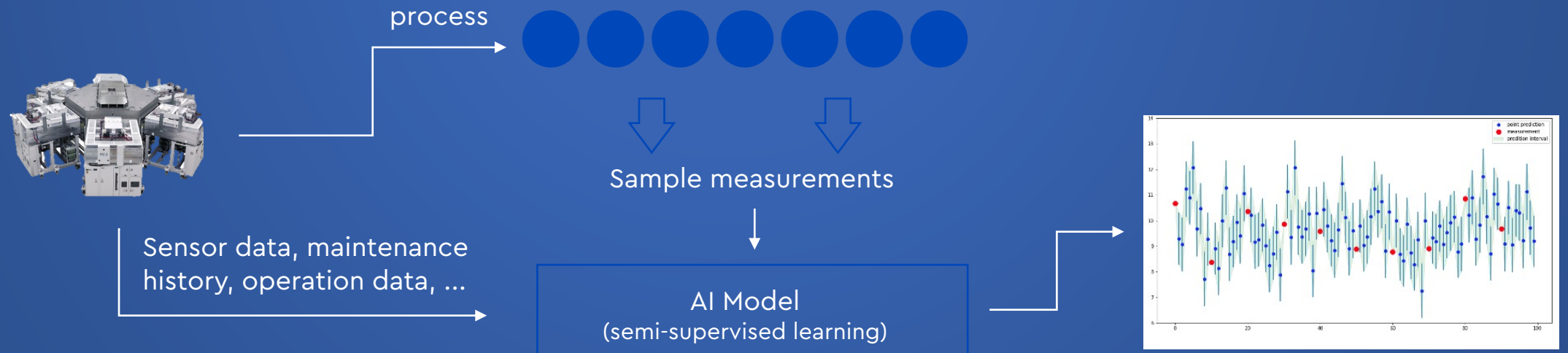
- measurement equipment is too expensive
- measuring every materials makes production slow inducing low throughput

*thus, we do sampling  
(with very low sampling rate)*

- in semiconductor manufacturing line, average sampling rate is less than 5%

## PROBLEM

- predict the measurement of unmeasured material using indirect signals
- sensor data, maintenance history, operation data, . . .



# Business Impact made by VM

## *To the best of our knowledge*

- no organization has even been successful with VM

## **Gauss Labs VM**

- uses online learning to cope with data drift/shift
- RMSE comparable to measurement equipment precision
- also predicts uncertainty of predictions - providing prediction reliability information

## **VM implications**

- measuring ALL wafers – equivalent to investing on 100x measurement equipment
- enables optimal re-allocation of limited measurement resources

# Conclusion

*supervised and unsupervised ML everywhere in industrial AI applications*

*lots of challenges*

- data challenge, domain knowledge required, need for customizing algorithms

*huge changes potentially made via various applications*

## **Impacts**

- Tens of Millions of dollars by 1% yield increase
- 100x measurement equipment save by VM